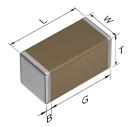
&TDK Multilayer Ceramic Chip Capacitors

C3216X5R0G107M160AB



TDK item description C3216X5R0G107MT****

Applications	Commercial Grade
Feature	General General (Up to 75V)
Series	C3216 [EIA 1206]
Status	Production



	Size
Length(L)	3.20mm +0.30,-0.10mm
Width(W)	1.60mm +0.30,-0.10mm
Thickness(T)	1.60mm +0.30,-0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	1.00mm Min.
Decommended Land Dattern (DA)	2.10mm to 2.50mm(Flow Soldering)
Recommended Land Pattern (PA)	2.00mm to 2.40mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.10mm to 1.30mm(Flow Soldering)
	1.00mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PC)	1.00mm to 1.30mm(Flow Soldering)
	1.10mm to 1.60mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	100µF ±20%	
Rated Voltage	4VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	1ΜΩ	

Other		
Coldering Mathed	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	2000pcs	

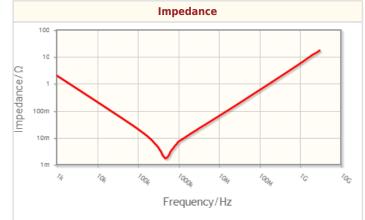
! Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

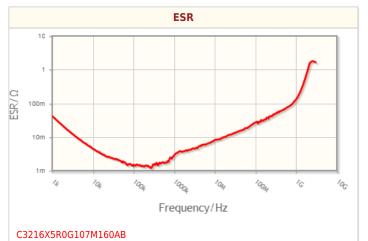
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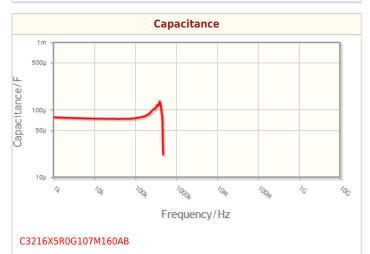


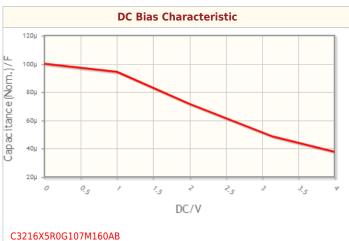


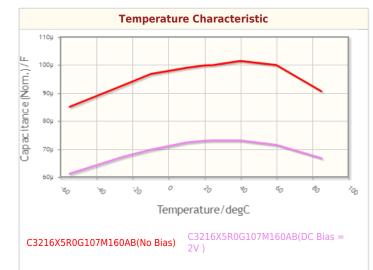
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

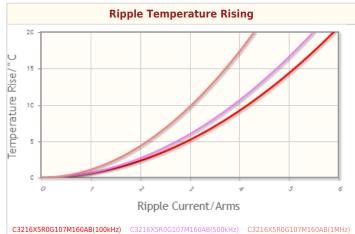


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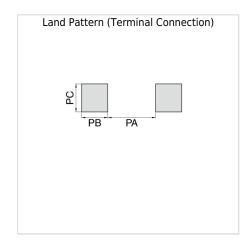
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Associated Images



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